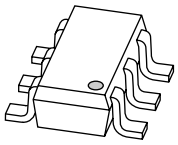


PBLS2002D

20 V PNP BISS loadswitch

Rev. 02 — 27 August 2009 Product data sheet

1. Product profile

1.1 General description

PNP low V_{CEsat} Breakthrough in Small Signal (BISS) transistor and NPN Resistor-Equipped Transistor (RET) in a SOT457 (SC-74) small Surface Mounted Device (SMD) plastic package.

1.2 Features

- Low V_{CEsat} (BISS) and resistor-equipped transistor in one package
- Low threshold voltage (< 1 V) compared to MOSFET
- Low drive power required
- Space-saving solution
- Reduction of component count

1.3 Applications

- Supply line switches
- Battery charger switches
- High-side switches for LEDs, drivers and backlights
- Portable equipment

1.4 Quick reference data

Table 1. Quick reference data

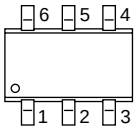
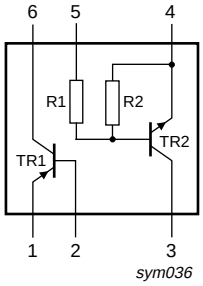
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
TR1; PNP low V_{CEsat} transistor							
V_{CEO}	collector-emitter voltage	open base		-	-	–20	V
I_C	collector current (DC)			-	-	–1	A
R_{CEsat}	collector-emitter saturation resistance	I_C = –1 A; I_B = –100 mA	[1]	-	185	280	mΩ
TR2; NPN resistor-equipped transistor							
V_{CEO}	collector-emitter voltage	open base		-	-	50	V
I_O	output current			-	-	100	mA
R1	bias resistor 1 (input)			3.3	4.7	6.1	kΩ
R2/R1	bias resistor ratio			0.8	1	1.2	

[1] Pulse test: $t_p \leq 300\ \mu s$; $\delta \leq 0.02$

NXP founded by Philips

2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Symbol
1	emitter TR1		
2	base TR1		
3	output (collector) TR2		
4	GND (emitter) TR2		
5	input (base) TR2		
6	collector TR1		

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PBLS2002D	SC-74	plastic surface mounted package; 6 leads	SOT457

4. Marking

Table 4. Marking codes

Type number	Marking code
PBLS2002D	F7

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
TR1; PNP low V_{CEsat} transistor						
V_{CBO}	collector-base voltage	open emitter		-	–20	V
V_{CEO}	collector-emitter voltage	open base		-	–20	V
V_{EBO}	emitter-base voltage	open collector		-	–5	V
I_C	collector current (DC)			-	–1	A
I_{CM}	peak collector current	$t_p \leq 300$ µs		-	–2	A
I_B	base current (DC)			-	–0.3	A
I_{BM}	peak base current	$t_p \leq 300$ µs		-	–0.6	A
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	[1]	-	250	mW
			[2]	-	350	mW
			[3]	-	400	mW

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Table 5. Limiting values *…continued*

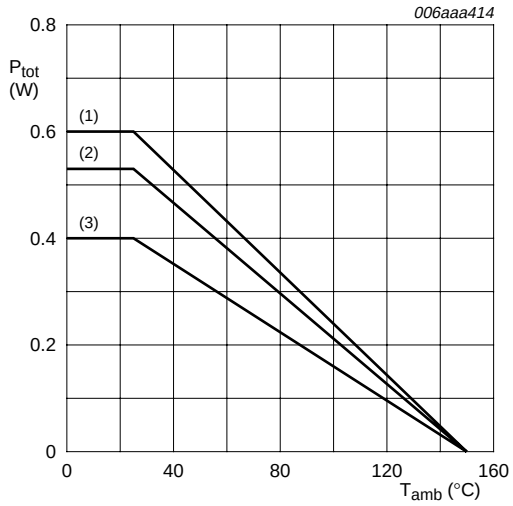
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
TR2; NPN resistor-equipped transistor						
V_{CBO}	collector-base voltage	open emitter		-	50	V
V_{CEO}	collector-emitter voltage	open base		-	50	V
V_{EBO}	emitter-base voltage	open collector		-	10	V
V_I	input voltage					
	positive			-	+30	V
	negative			-	–10	V
I_O	output current			-	100	mA
I_{CM}	peak collector current	$t_p \leq 300$ µs		-	100	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	[1]	-	200	mW
Per device						
P_{tot}	total power dissipation		[1]	-	400	mW
			[2]	-	530	mW
			[3]	-	600	mW
T_{stg}	storage temperature			–65	+150	°C
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			–65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1cm^2.

[3] Device mounted on a ceramic PCB, Al_2O_3, standard footprint.



(1) Ceramic PCB, Al_2O_3, standard footprint

(2) FR4 PCB, mounting pad for collector 1cm^2

(3) FR4 PCB, standard footprint

Fig 1. Power derating curves

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6. Thermal characteristics

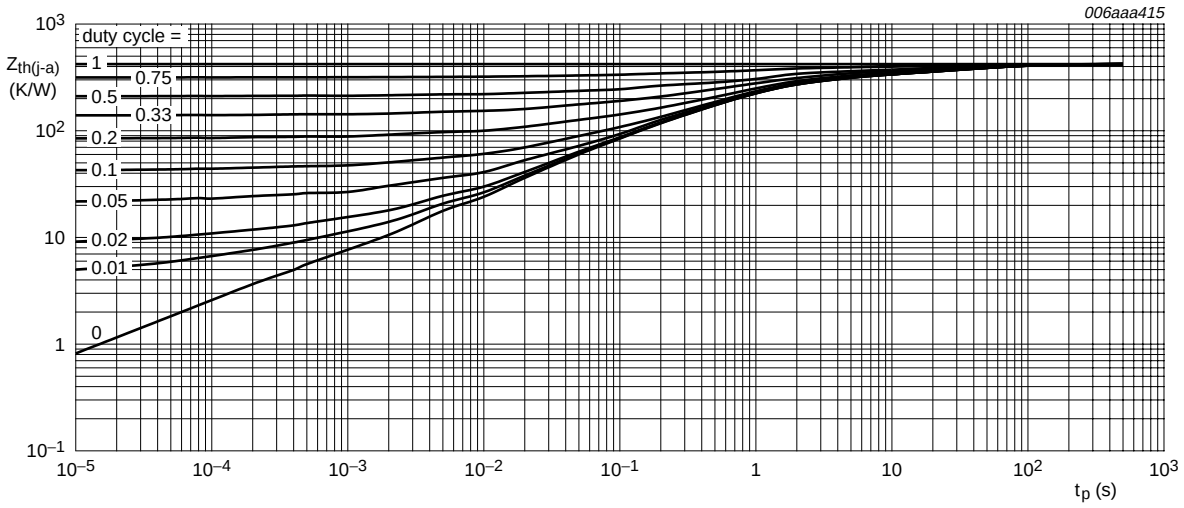
Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Per device							
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	-	315	K/W
			[2]	-	-	236	K/W
			[3]	-	-	210	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1cm^2.

[3] Device mounted on a ceramic PCB, Al_2O_3, standard footprint.



FR4 PCB, standard footprint

Fig 2. TR1 (PNP): Transient thermal impedance from junction to ambient as a function of pulse time; typical values

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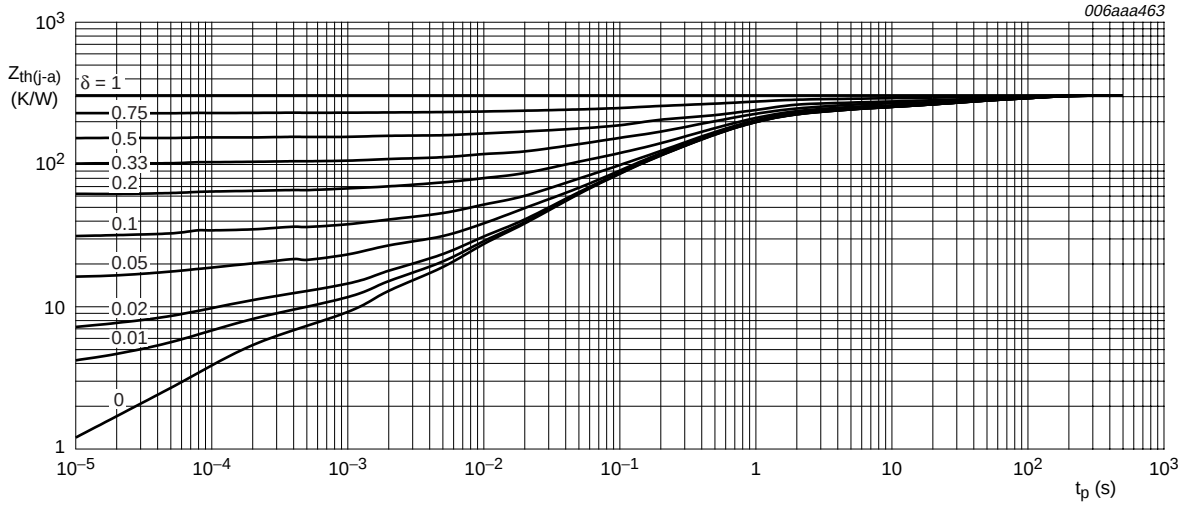
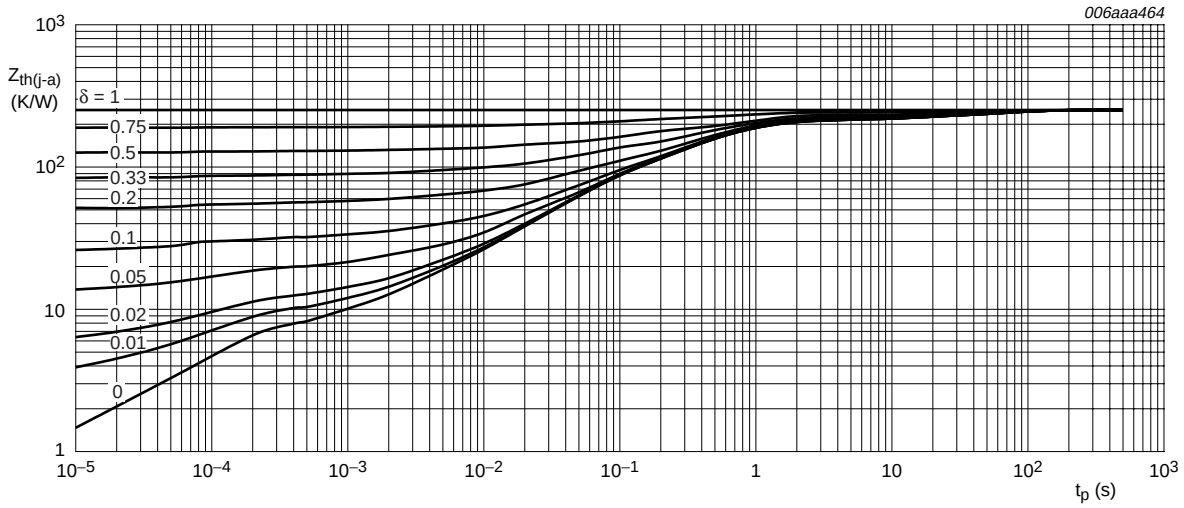


FR4 PCB, mounting pad for collector 1cm^2

Fig 3. TR1 (PNP): Transient thermal impedance from junction to ambient as a function of pulse time; typical values



Ceramic PCB, Al_2O_3, standard footprint

Fig 4. TR1 (PNP): Transient thermal impedance from junction to ambient as a function of pulse time; typical values

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7. Characteristics

Table 7. Characteristics

T_{amb} = 25 °C unless otherwise specified

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
TR1; PNP low V_{CEsat} transistor							
I_{CBO}	collector-base cut-off current	V_{CB} = –20 V; I_E = 0 A		-	-	–0.1	µA
		V_{CB} = –20 V; I_E = 0 A; T_j = 150 °C		-	-	–50	µA
I_{CES}	collector-emitter cut-off current	V_{CE} = –20 V; V_{BE} = 0 V		-	-	–0.1	µA
I_{EBO}	emitter-base cut-off current	V_{EB} = –5 V; I_C = 0 A		-	-	–0.1	µA
h_{FE}	DC current gain	V_{CE} = –2 V; I_C = –1 mA		220	495	-	
		V_{CE} = –2 V; I_C = –100 mA		220	440	-	
		V_{CE} = –2 V; I_C = –500 mA	[1]	220	310	-	
		V_{CE} = –2 V; I_C = –1 A	[1]	155	220	-	
		V_{CE} = –2 V; I_C = –2 A	[1]	60	120	-	
V_{CEsat}	collector-emitter saturation voltage	I_C = –100 mA; I_B = –1 mA		-	–55	–90	mV
		I_C = –500 mA; I_B = –50 mA	[1]	-	–100	–150	mV
		I_C = –1 A; I_B = –50 mA	[1]	-	–200	–300	mV
		I_C = –1 A; I_B = –100 mA	[1]	-	–185	–280	mV
R_{CEsat}	collector-emitter saturation resistance	I_C = –1 A; I_B = –100 mA	[1]	-	185	280	mΩ
V_{BEsat}	base-emitter saturation voltage	I_C = –1 A; I_B = –50 mA	[1]	-	–0.95	–1.1	V
		I_C = –1 A; I_B = –100 mA	[1]	-	–1	–1.1	V
V_{BEon}	base-emitter turn-on voltage	V_{CE} = –5 V; I_C = –1 A	[1]	-	–0.85	–1.1	V
t_d	delay time	I_C = –1 A; I_{Bon} = –50 mA; I_{Boff} = 50 mA		-	8	-	ns
t_r	rise time			-	34	-	ns
t_{on}	turn-on time			-	42	-	ns
t_s	storage time			-	140	-	ns
t_f	fall time			-	45	-	ns
t_{off}	turn-off time			-	185	-	ns
f_T	transition frequency	I_C = –50 mA; V_{CE} = –10 V; f = 100 MHz		150	185	-	MHz
C_c	collector capacitance	V_{CB} = –10 V; I_E = i_e = 0 A; f = 1 MHz		-	15	20	pF

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Table 7. Characteristics *...continued*

T_{amb} = 25 °C unless otherwise specified

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
TR2; NPN resistor-equipped transistor						
I_{CBO}	collector-base cut-off current	V_{CB} = 50 V; I_E = 0 A	-	-	100	nA
I_{CEO}	collector-emitter cut-off current	V_{CE} = 30 V; I_B = 0 A	-	-	1	µA
		V_{CE} = 30 V; I_B = 0 A; T_j = 150 °C	-	-	50	µA
I_{EBO}	emitter-base cut-off current	V_{EB} = 5 V; I_C = 0 A	-	-	900	µA
h_{FE}	DC current gain	V_{CE} = 5 V; I_C = 10 mA	30	-	-	
V_{CEsat}	collector-emitter saturation voltage	I_C = 10 mA; I_B = 0.5 mA	-	-	150	mV
$V_{I(off)}$	off-state input voltage	V_{CE} = 5 V; I_C = 100 µA	-	1.1	0.5	V
$V_{I(on)}$	on-state input voltage	V_{CE} = 0.3 V; I_C = 20 mA	2.5	1.9	-	V
R1	bias resistor 1 (input)		3.3	4.7	6.1	kΩ
R2/R1	bias resistor ratio		0.8	1	1.2	
C_c	collector capacitance	V_{CB} = 10 V; I_E = i_e = 0 A; f = 1 MHz	-	-	2.5	pF

[1] Pulse test: $t_p \leq 300$ µs; $\delta \leq 0.02$

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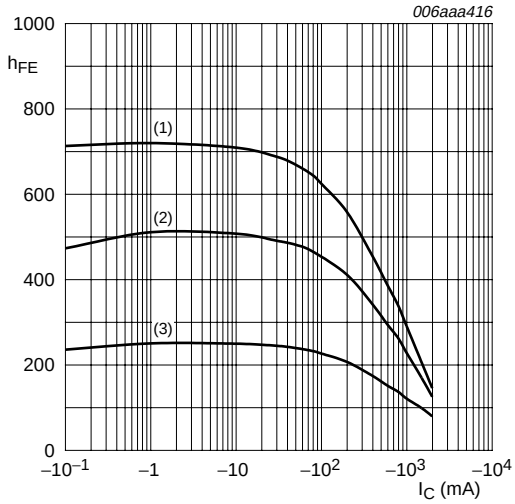


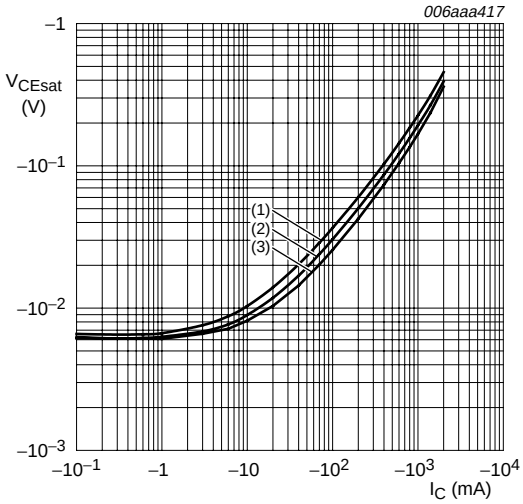
V_{CE} = –2 V

(1) T_{amb} = 100 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = –55 °C

Fig 5. TR1 (PNP): DC current gain as a function of collector current; typical values



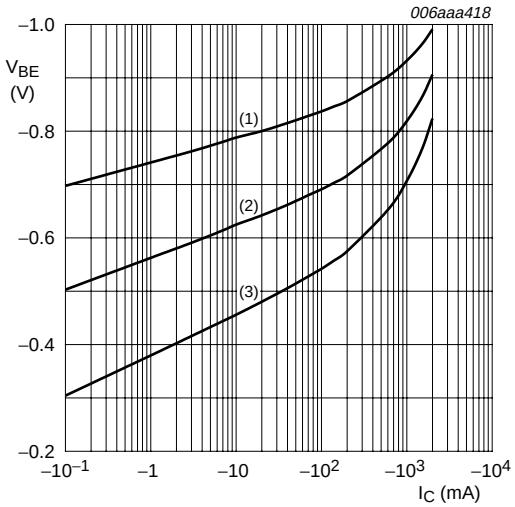
I_C/I_B = 20

(1) T_{amb} = 100 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = –55 °C

Fig 6. TR1 (PNP): Collector-emitter saturation voltage as a function of collector current; typical values



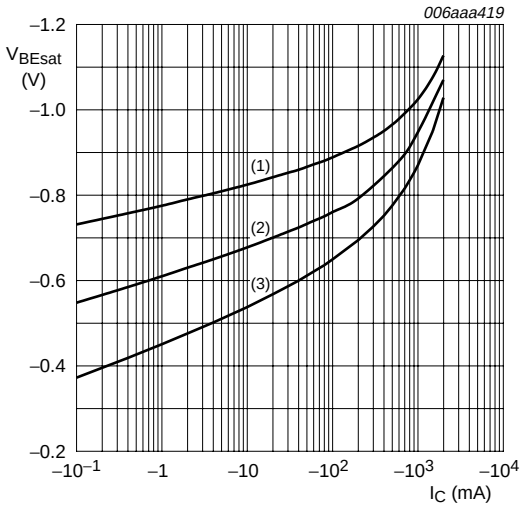
V_{CE} = –5 V

(1) T_{amb} = –55 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = 100 °C

Fig 7. TR1 (PNP): Base-emitter voltage as a function of collector current; typical values



I_C/I_B = 20

(1) T_{amb} = –55 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = 100 °C

Fig 8. TR1 (PNP): Base-emitter saturation voltage as a function of collector current; typical values

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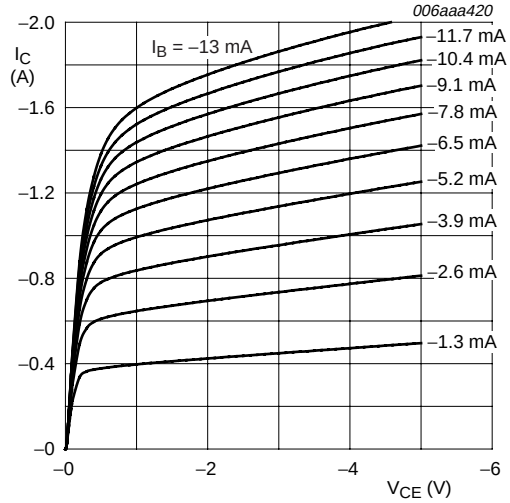
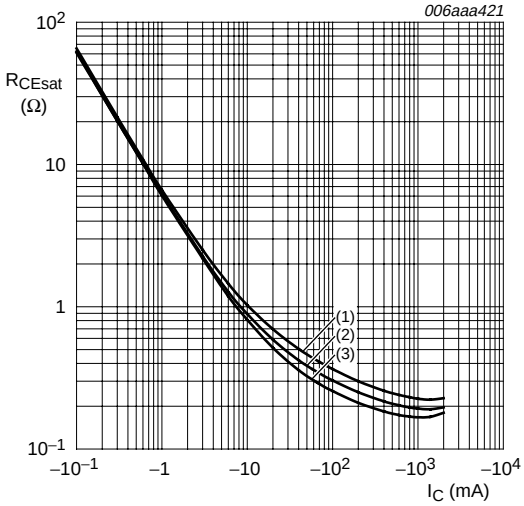


T_{amb} = 25 °C

Fig 9. TR1 (PNP): Collector current as a function of collector-emitter voltage; typical values



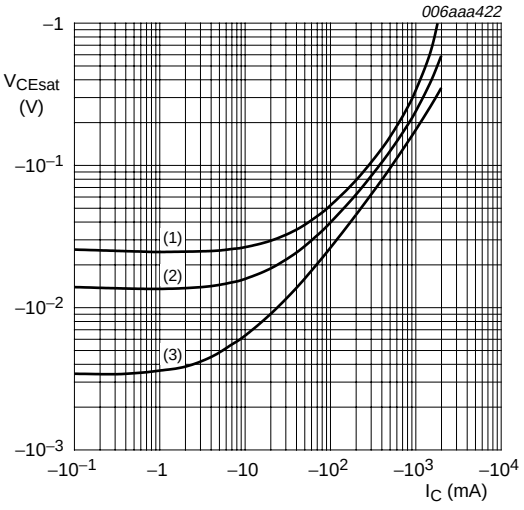
I_C/I_B = 20

(1) T_{amb} = 100 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = −55 °C

Fig 10. TR1 (PNP): Collector-emitter saturation resistance as a function of collector current; typical values



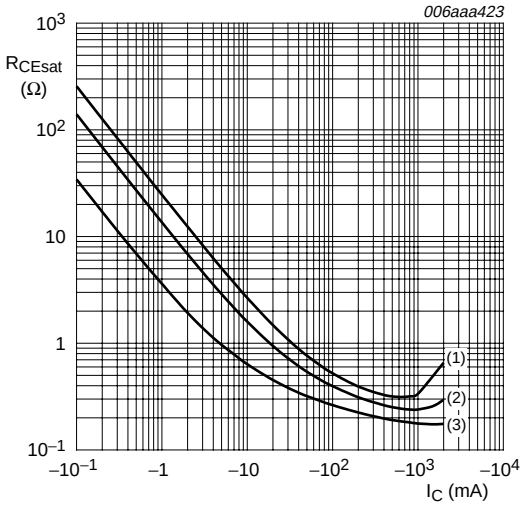
T_{amb} = 25 °C

(1) I_C/I_B = 100

(2) I_C/I_B = 50

(3) I_C/I_B = 10

Fig 11. TR1 (PNP): Collector-emitter saturation voltage as a function of collector current; typical values



T_{amb} = 25 °C

(1) I_C/I_B = 100

(2) I_C/I_B = 50

(3) I_C/I_B = 10

Fig 12. TR1 (PNP): Collector-emitter saturation resistance as a function of collector current; typical values

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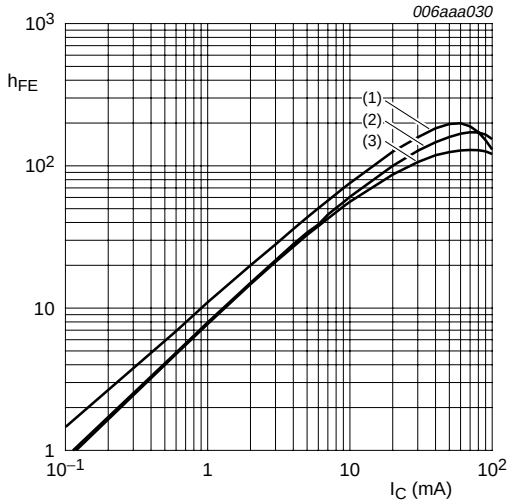


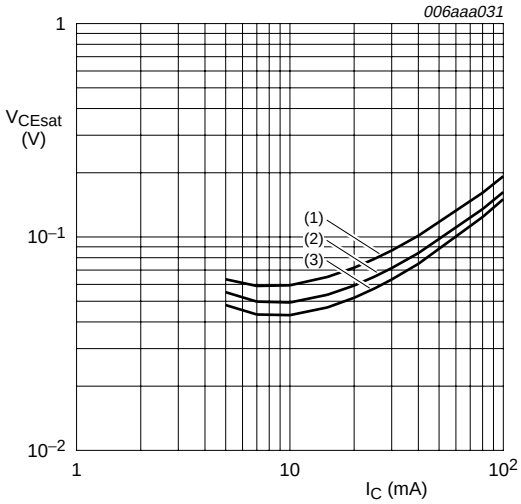
V_{CE} = 5 V

(1) T_{amb} = 150 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = –40 °C

Fig 13. TR2 (NPN): DC current gain as a function of collector current; typical values



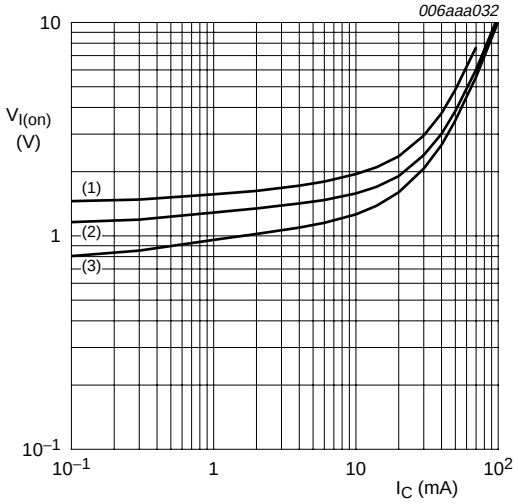
I_C/I_B = 20

(1) T_{amb} = 100 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = –40 °C

Fig 14. TR2 (NPN): Collector-emitter saturation voltage as a function of collector current; typical values



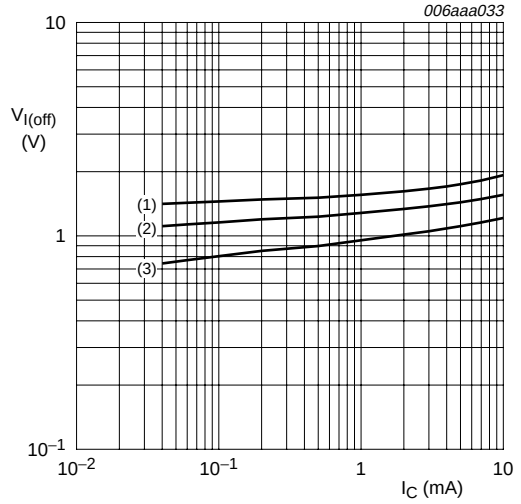
V_{CE} = 0.3 V

(1) T_{amb} = –40 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = 100 °C

Fig 15. TR2 (NPN): On-state input voltage as a function of collector current; typical values



V_{CE} = 5 V

(1) T_{amb} = –40 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = 100 °C

Fig 16. TR2 (NPN): Off-state input voltage as a function of collector current; typical values

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8. Test information

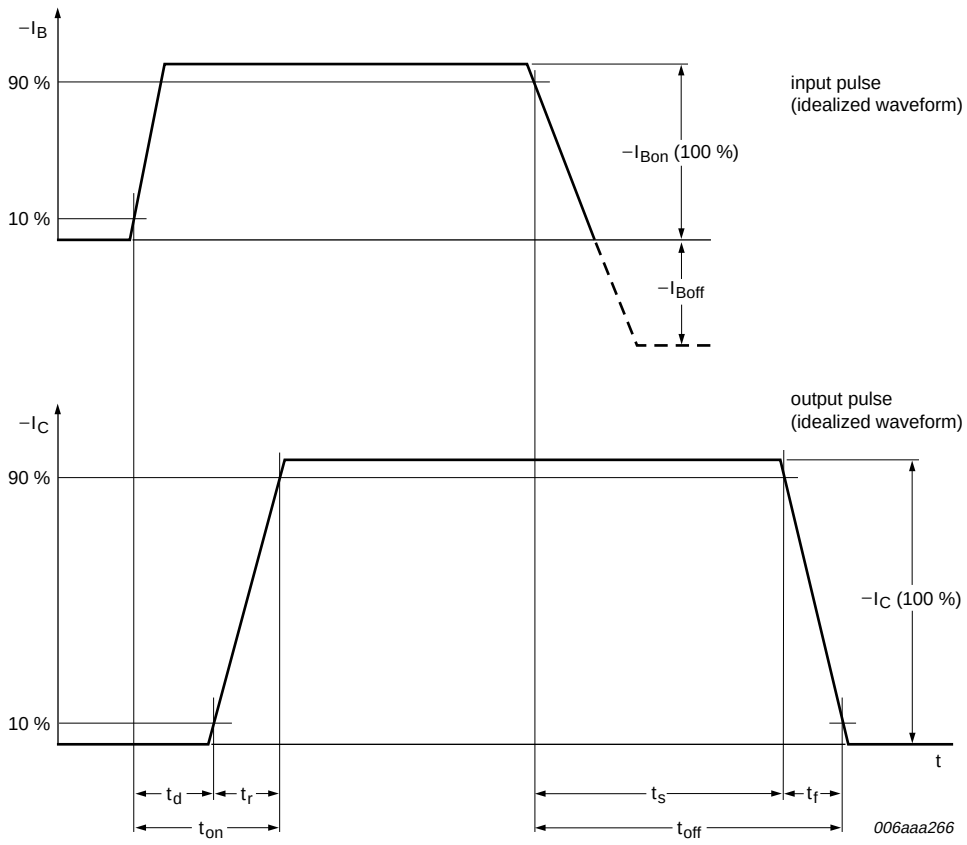
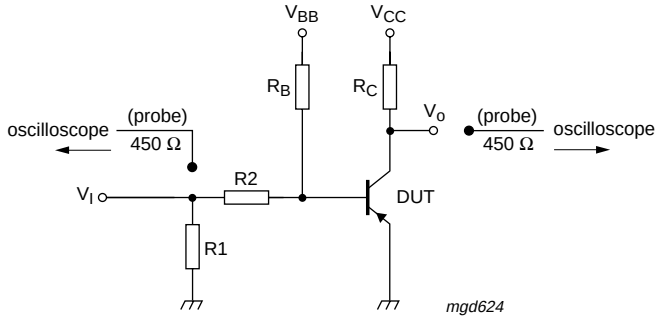


Fig 17. BISS transistor switching time definition



I_C = −1 A; I_{Bon} = −50 mA; I_{Boff} = 50 mA; R1 = open; R2 = 45 Ω; R_B = 145 Ω; R_C = 10 Ω

Fig 18. Test circuit for switching times

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9. Package outline

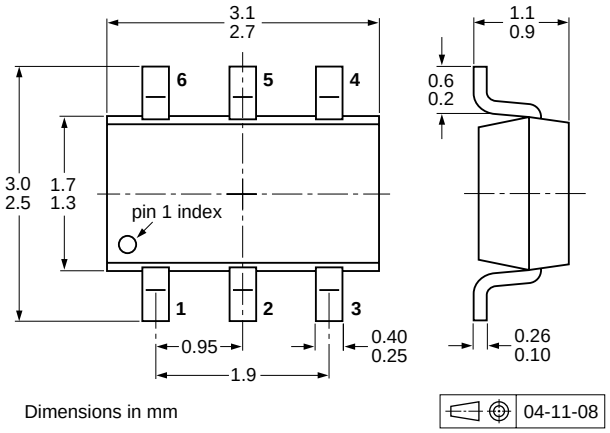

Fig 19. Package outline SOT457 (SC-74)

10. Packing information

Table 8. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.[1]

Type number	Package	Description		Packing quantity	
				3000	10000
PBLS2002D	SOT457	4 mm pitch, 8 mm tape and reel; T1	[2]	-115	-135
		4 mm pitch, 8 mm tape and reel; T2	[3]	-125	-165

[1] For further information and the availability of packing methods, see Section 14.

[2] T1: normal taping

[3] T2: reverse taping

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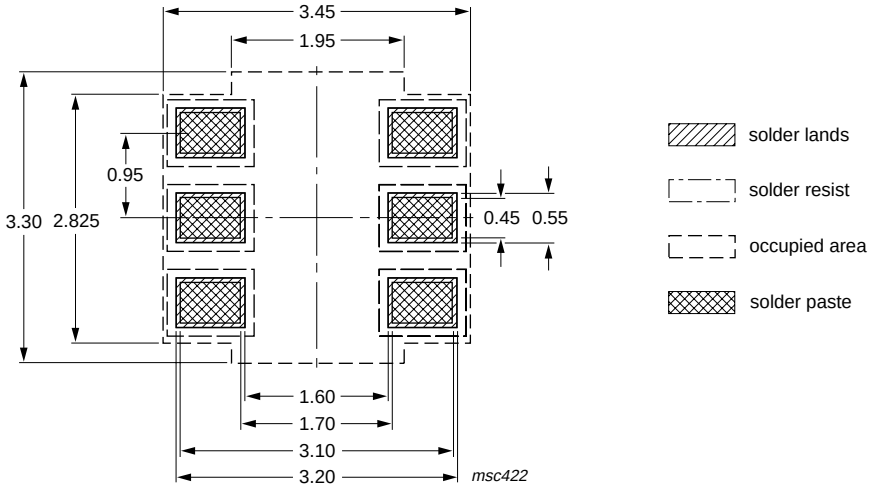
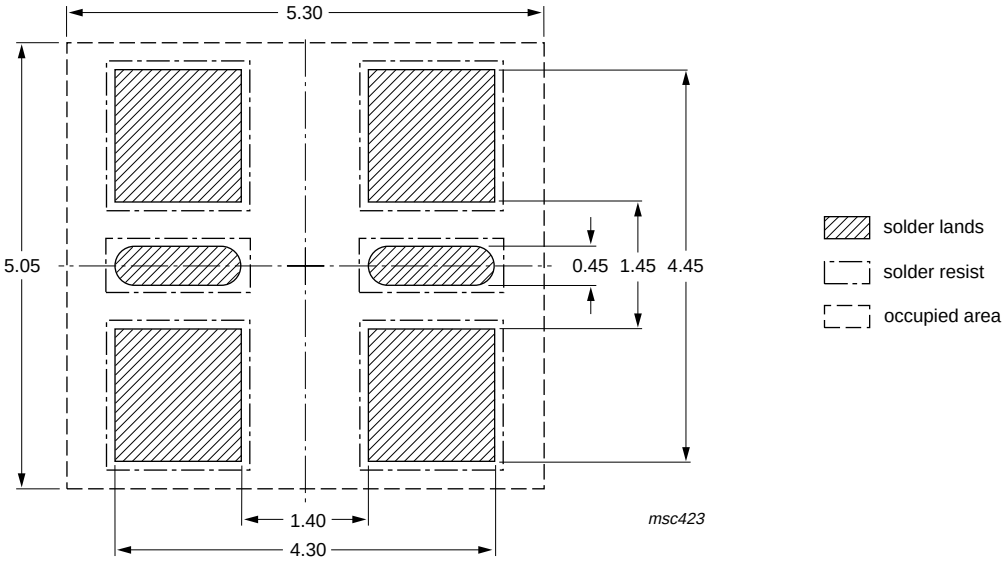
11. Soldering



Dimensions in mm

Fig 20. Reflow soldering footprint



Dimensions in mm

Fig 21. Wave soldering footprint

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12. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PBLS2002D_2	20090827	Product data sheet	-	PBLS2002D_1
Modifications:	• This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content. • Figure 21 “Wave soldering footprint”: updated			
PBLS2002D_1	20050623	Product data sheet	-	-

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13. Legal information

13.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

13.2 Definitions

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